



ITONFIEXHCI The Next-Generation Hyperconverged Infrastructure



Modernize Your IT with IronFlex HCI

IronFlex Hyper-Converged Infrastructure

IronFlex combines compute, storage, and networking into a single, unified system, enabling data centers to scale effortlessly while enhancing performance, streamlining operations, and reducing complexity, all while ensuring higher efficiency and flexibility.

Speed Scalability Reliability

FRANSFORMING DATA CENTERS
– POWERED BY RAKUTEN CLOUD"

IronFlex HCI based Cloud for VM and Cloud-native workloads with best-in-class TCO

IronFlex HCI Features

IronFlex powered by Rakuten Cloud unifies compute, storage, and networking, enabling scalable, high-performance & simplified data center operations.





Optimized for Deployment & management of mission critical applications



Proven best-in-class performance versus competition

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Multi-site, multi-environment orchestration with single pane of glass



Simplified application and network function delivery and life cycle management, integrated App Store

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Common Platform to run containerized or virtualized Network functions & applications



Advanced data management including Snapshots, Clone, Replication, BCDR and en<u>cryption</u>



Highly efficient Kubernetes cloud that with minimal footprint for edge use cases



Centralized Metal to Service orchestration of network services with automated LCM

Why IronFlex Stands Out ?



Unified Management Single-pane-of-glass visibility for monitoring & control



Faster Deployment Rapid setup & provisioning



Scalable & Flexible Expand as your business grows



Data Protection Built-in disaster recovery & backup.



Cloud Integration Seamless hybrid cloud support.



Secure Environment Enterprise-grade security features.



Business Benefits

Lower TCO (Capex & Opex Savings) Better IOPS for Performance-Intensive Applications Flexible Licensing & Multi-Tenancy Support Application-Aware QoS for Optimized Workloads

Use Cases & Industry Applications

Designed for Every Industry:





Enterprise IT

Run mission-critical applications with high reliability.



Gaming & Media

High-speed processing & storage for real-time applications.



Healthcare

Secure, high-performance infrastructure for patient data.



Financial Services

Low-latency, highsecurity environment for transactions



Cloud Service Providers

Multi-tenant architecture with flexible scaling



Manufacturing

Host applications for automated inspection and logging.

SKU's

HCI Series	Details	Specifications	Available SKUs
General Purpose - E Series	Entry Level	Single CPU/Dual CPU per host	IF-E4116
		CPU from 8 Core to 24 Core	IF-E4120
		Memory upto 256 GB per host	IF-E4124
B Series	Optimized Compute and Storage	Single CPU/Dual CPU per host	IF-B4128
		CPU from 24 core to 56 Core	IF-B4132
		Memory upto 1024 GB per host	IF-B4148
H Series	High Performance Use cases	Single CPU/Dual CPU per host	IF-HG4264
		CPU core 64 to 128 core	IF-HG4296
		Memory from 1024 to 6TB Per Host	IF-HG42128

IronFlex Specifications

FEATURES	PARAMETER	DESCRIPTION	
Processor	Supported CPU Series	Supports up to 2 processors of AMD EPYC 9004 series (Generation 4)	
		Min 16 Core – Max 128 Core per Processor (Boost clock Up to 3.7GHz)	
	Thermal Design Power (TDP) wattage	Up to 400W TDP, L3 CACHE - 384MB	
Chipset	AMD	AMD EPYC™ GENOA/BERGAMO	
Front hard drive	Storage	Supports 24 x 2.5" drives	
		(SATA Per port 1.92TB @ 6Gb/s)	
		(NVMe per port 30.72TB) (M.2 per port 1.92TB)	
		16 NVMe + 8 SATA	
		24 – SATA with RAID CARD Support	
		2 SLOTS M.2(SATA) + 1 SLOT M.2(NVMe)	
Dimensions	W x H x D (mm)/Weight	450 x 88 x 780 / 35KG	
BMC chip	ASIC	AST2600	
Memory	Max DIMM slots	1 DIMMs/CH, 12 CH/CPU, Total 24 DIMMs	
	DIMM type	DDR5 RDIMMs or LRDIMMs	
	Memory Capacity	16/32/64/128 GB, up to total 3TB capacity	
	Memory Speed	Support upto 4800 MHz	
	Memory Voltage	1.IV	
External port & PCIe	Front I/O	Front Port: 1 VGA, 2 USB 3.2 Gen1	
	Rear I/O	Rear: 1 MINI DP, 1 COM port, 2 USB3.2 Gen1, 1 management network	
	PCle	PCIe expansion slots:	
		2 PCIe Gen5.0 full-height slots	
		1 PCIe Gen5.0 full-height Half Length slot	
		OCP slot: 1 PCIe 3.0 x16, Mezzanine slot	

FEATURES	PARAMETER	DESCRIPTION	
Networking	Ethernet	1G*1 management network port On-board 1G*1 onboard LOM	
	OCP 3.0	1/10/25/40/100G network port with OCP 3.0 add-on card	
	Rear I/O	RJ45 1G 1 Port *1,Mini Display port, Micro USB Type-C, UID button with integrated LED,	
	ROT Module	I2C/I3C/GPIO connectivity to 'host Node CPUs' and BMC/CMC	
DC_SCM		Runtime SPI and I2C/SMBus monitoring and filtering	
	Storage	• M.2 2230 M-Key	
		IMicro-SD storage device, connected to BMC/CMC	
Display	LCD Display	* Supports Post code debug through on-board LCD display	
	GPU	Up to 3x double width 350W GPU and Up to 8x single width 75W GPU	
	RAID	Hardware RAID flash cache; HBAs	
External Cards	NIC	X4, X8 and X16 FHHL and HHHL NIC support, Rj45 - 1G & 10G - Maximum 4 port support	
		SFP+ - 10Gb/s Per Port , QSFP56 - 200Gb/s Per Port	
	Backplane	U.2/U.3 Based connector for drive insertion	
Drive Control		Hot swappable	
		LED management using UBM controller	
Power Supply	Redundancy	1+1	
	Input Range	Full range AC (100 - 240 VAC)	
	Output Watts	1600W/2200W/2700W	
	Efficiency	Titanium	
Chassis	Form Factor	2U Rack Mountable	
BIOS/BMC	BRAND	AMI/ OpenBmc	
os	OS Supported	Red Hat Enterprise Linux, Rocky Linux	
Security	трм 2.0	TPM/TCM (optional),Locked upper cover of chassis	
	ROT (Root of Trust)	NIST SP 800-193 (For platform firmware resilience (PFR))	
Intelligent temp. control	Temperature control	FPGA Based PWM fan control	
System Cooling	FAN	6 hot swap system 60x60mm fans,60W	
Software	IronCore CNP, CNS and CNO - Powered by Rakuten Cloud	Rakuten cloud compatible with Red Hat Enterprise Linux, Rocky Linux	
Operating Environment	Operating Temp	5°C - 35°C (indoor)	
	Non-Operating Temp	-40°C - 70°C	
Humidity	Operating relative humidity Non- operating relative humidity	20% - 80%	
		10% - 95%	
ROHS COMPLAINT	RoHS 6/6 Complaint	Yes	

Manufactured at velankani



Get Started with IronFlex.

CONTACT

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